SUSS MICROTEC INVESTOR PRESENTATION

February 2019

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

AGENDA

1. Overview
2. Strategy, products and markets
3. Financials
4. Outlook

AGENDA

1 **Overview**

2 Strategy, products and markets

3 Financials

4 Outlook

HIGHLIGHTS AND PRELIMINARY NUMBERS FY 2018

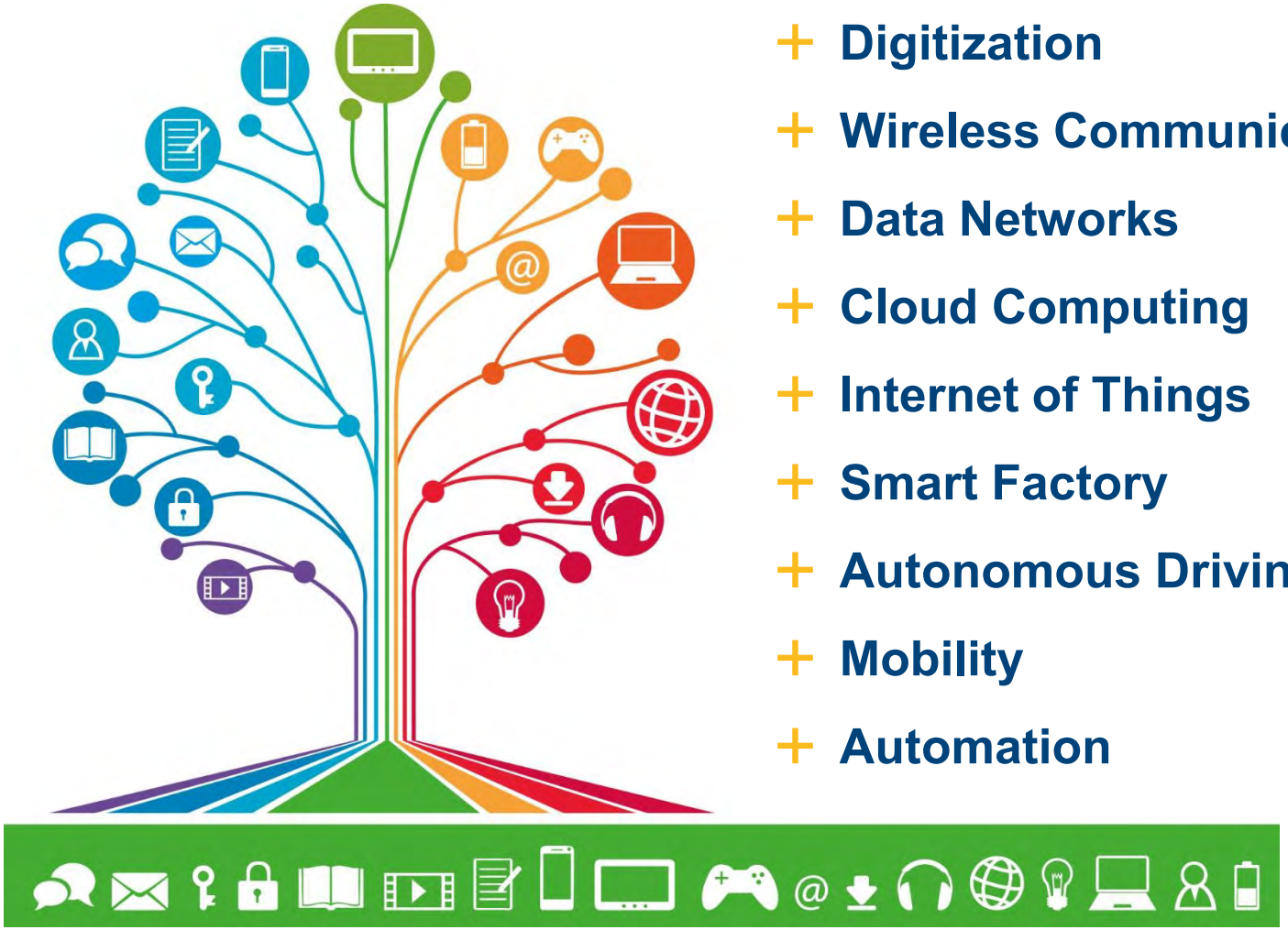
- **Announcement of growth strategy: SUSS 2025**
- **Good order entry for high-end photomask equipment**
- **3D-integration is accelerating and turning bonder business into profitability**
- **Delivery of UV-scanner evaluation tool to leading Asian semiconductor manufacturer**

in € million	delta 2018 (IFRS15) / 2017	2018 (IFRS15)	2018 (old)	2017	2016
Order Intake	**-4.6%**	**191.0**	**191.0**	**200.3**	**161.1**
Revenue	**+20%**	**~200**	**~213**	**166.5**	**177.6**
EBIT*	**-40%**	**~8.4**	**~15.5**	**13.9**	**11.1**
EBIT in % of Sales	*-4%pts*	*~4.2%*	*~7.3%*	*8.3%*	*6.3%*
Net Cash	**-14.5%**	**28.2**	**28.2**	**33.0**	**31.1**

SUSS MICROTEC TODAY

- Equipment provider for semiconductor and related industries
- Semi front-, mid- and back-end, MEMS, RF, Opto, etc.
- Tier one market players becoming major customers
- Very demanding market environment

MARKET ENVIRONMENT - MEGATRENDS



+ Digitization
+ Wireless Communication
+ Data Networks
+ Cloud Computing
+ Internet of Things
+ Smart Factory
+ Autonomous Driving
+ Mobility
+ Automation

SUSS MICROTEC – A GLOBAL PLAYER

MAIN PRODUCTION SITES

Germany

Sternenfels*

+ **Development/production:**
  - Bonder
  - Coater and Developer
  - Photomask Equipment
+ **Core competencies:**
  - Wet Processing
  - Wafer Bonding
  - Photomask Equipment
+ **Production facility ~15,000 m²**

Garching*

+ **SUSS MicroTec HQ**
+ **Development/production:**
  - Mask Aligner
  - Bond Aligner
+ **Core competencies:**
  - Exposure (proximity exposure)
  - Alignment
  - Bond Aligner
+ **Production facility ~9,000 m²**

Switzerland

Neuchatel (Switzerland)

+ **Core competencies:**
  - Production of micro-optical components
  - Imprint Excellence Center
+ **Production facility ~1,200 m²**
+ **2 sites for redundancy**

USA

Corona (California)

+ **Development/production:**
  - Stepper/Scanner
  - Laser Processing
+ **Core competencies:**
  - Exposure (UV projection)
  - Laser Ablation
+ **Production facility ~7,000 m²**

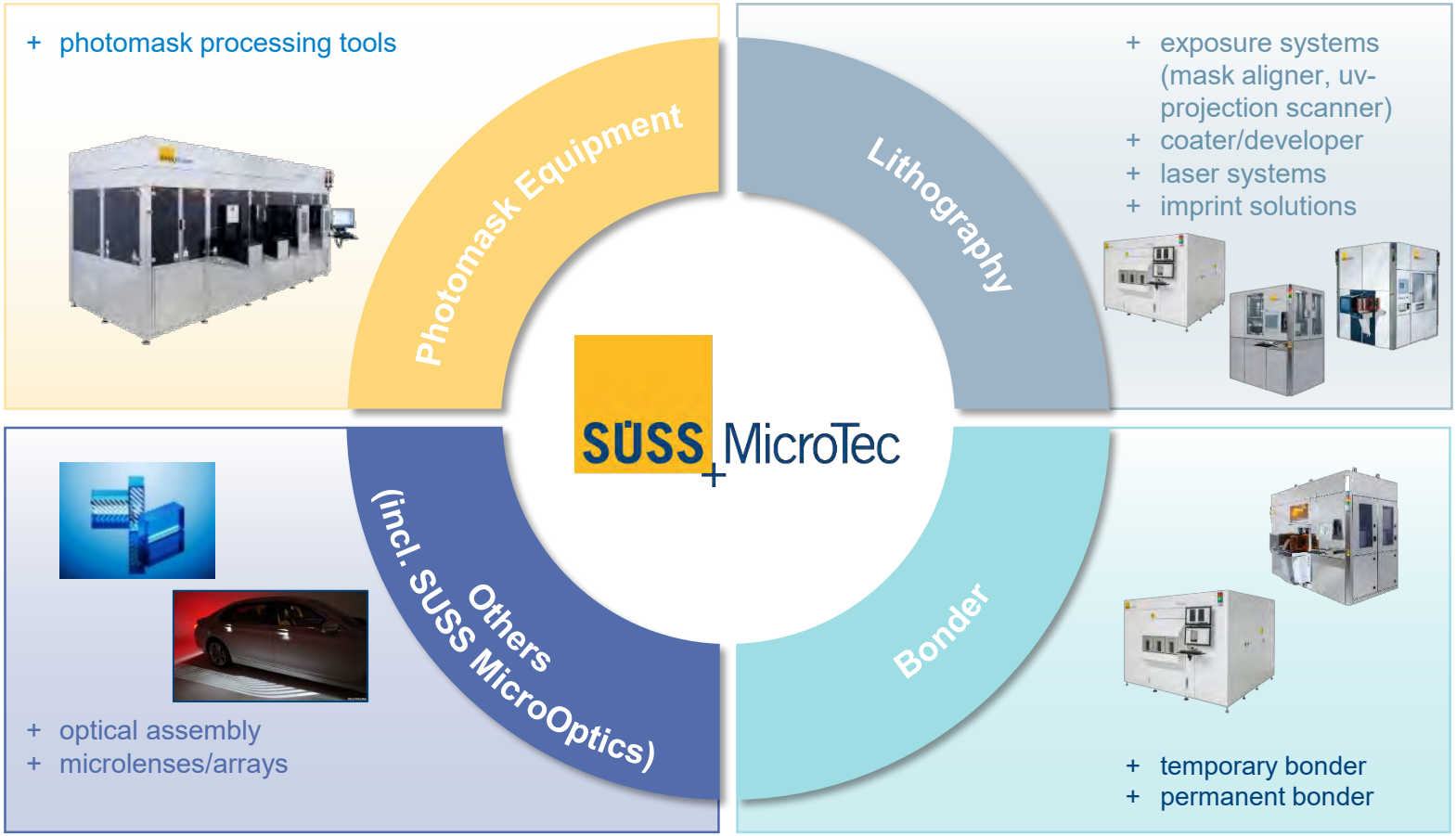
Taiwan

HsinChu (Taiwan)**

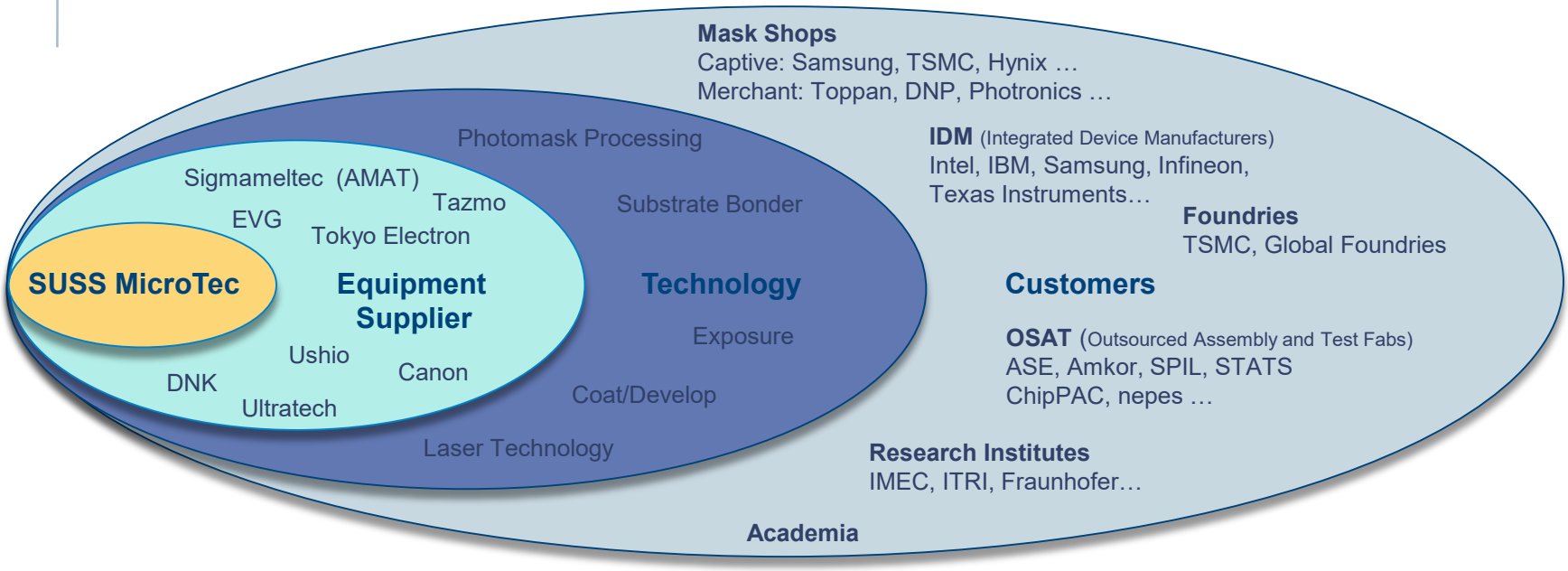
+ **Core competencies:**
  - Final Assembly Coater
  - Application
  - Show Room

*Production site is owned by SUSS MicroTec
**planned

OUR PRODUCT PORTFOLIO



MAIN COMPETITORS AND PEER GROUP



Peer Group

BE Semiconductor:	equipment for leadframe, substrate and WLP applications (die attach, wire-bonding, plating), target markets include electronics, computer, automotive, industrial, LED and solar energy
Veeco/UTEC:	steppers for the semiconductor market, advanced packaging, nanotechnology, laser processing (LSA)
Kulicke & Soffa:	design and manufacture of equipment for semiconductor, LED and electronic assembly (wire-bonding, advanced packaging)
Rudolph Tech:	equipment and software solutions for macro defect inspection, probe card test and analysis, thin film metrology, advanced packaging lithography systems (steppers)
EV Group:	equipment for wafer-bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection for the target markets: advanced packaging, compound semiconductor and silicon-based power devices, MEMS, nanotechnology and SOI

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1 Overview

2 Strategy, products and markets

3 Financials

4 Outlook

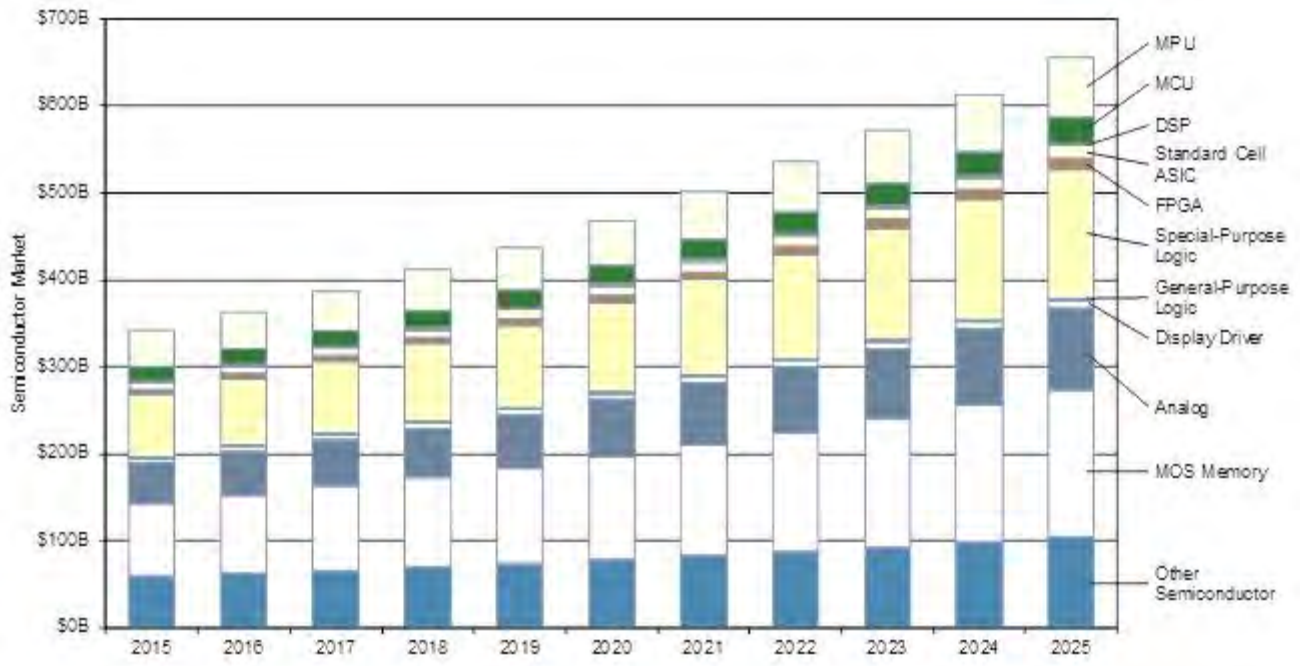
MARKETS ARE CHANGING – WE RECOGNIZE AND WE REALIZE OPPORTUNITIES

- Megatrends are driving our business: digitization, wireless communication (5G), data networks, cloud computing, IoT, smart factory, autonomous driving, mobility, AI
- Semiconductor industry is highly innovative and very demanding
- Processes are getting more complex – customers asking for more support
- News business fields arise:
  - UV – projection scanners for advanced packaging, esp. FOWLP
  - Imprint solutions for production of optical elements
  - SUSS MicroOptics products for the automotive industry

OUR KEY GROWTH DRIVERS

Market	Advanced packaging	(RF) MEMS	Chipset integration	MicroOptics
	- Micro-bumping - CU-pillar - Redistribution layer (RDL) - FOWLP	- SAW/BAW filters for 5G standard - Autonomous driving - Mobile devices - Smart factory	- 3D TSV - 2.5D integration	- Automotive light carpet - Optical assembly - Wafer level optics
SUSS Products	- Coater/developer - UV - scanner	- Coater/developer - UV - scanner	- Temporary bonder - Coater/developer	- Mask Aligner platform for imprint solutions/ lens stacking

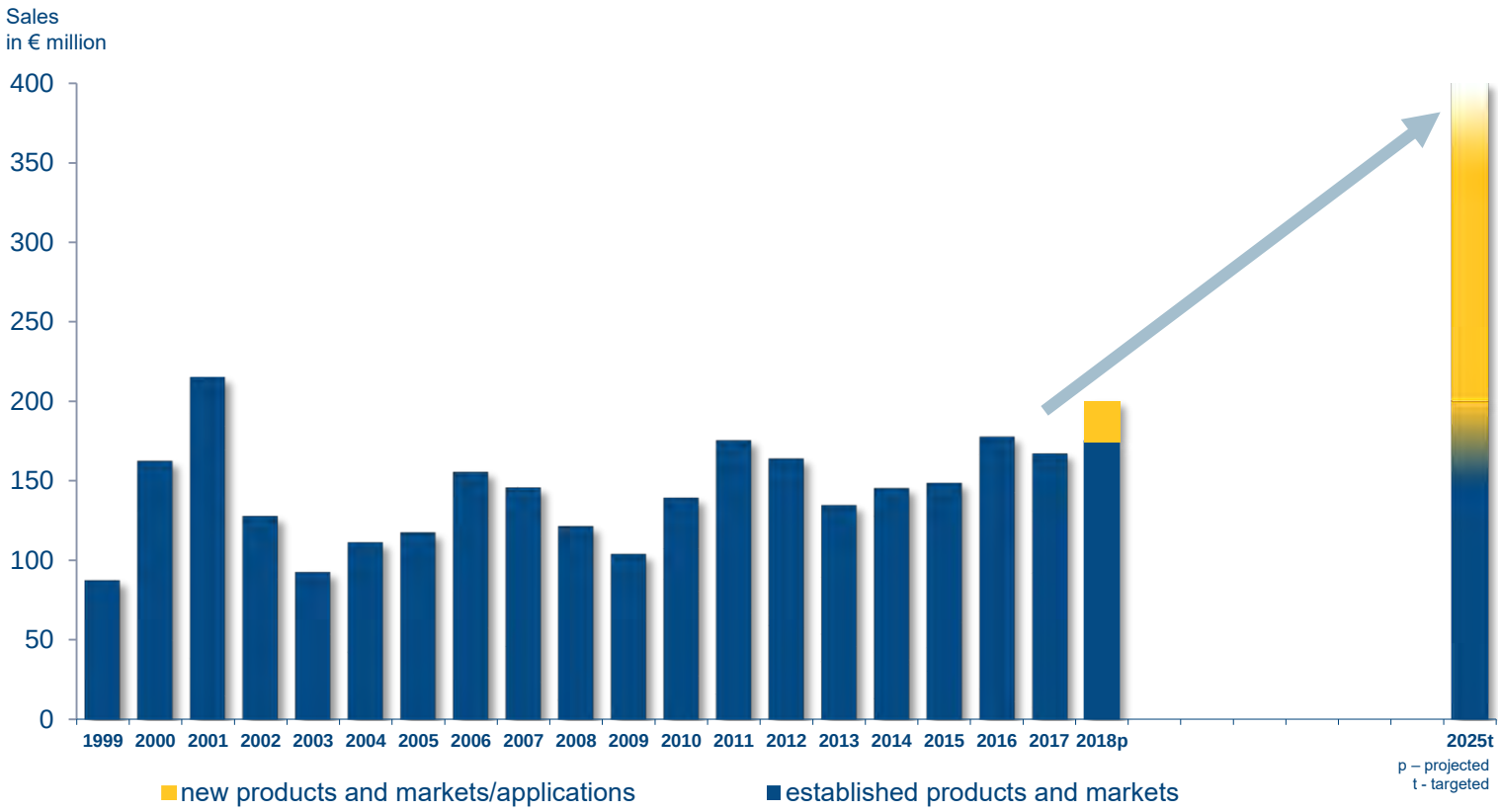
SEMICONDUCTOR MARKET LONG TERM OUTLOOK



The global semiconductor market will be $656B in 2025 compared to $343B in 2015 with a CAGR of 6.7%*

*source Semi.org

SEMICONDUCTOR MARKET OUTLOOK = SUSS POTENTIAL



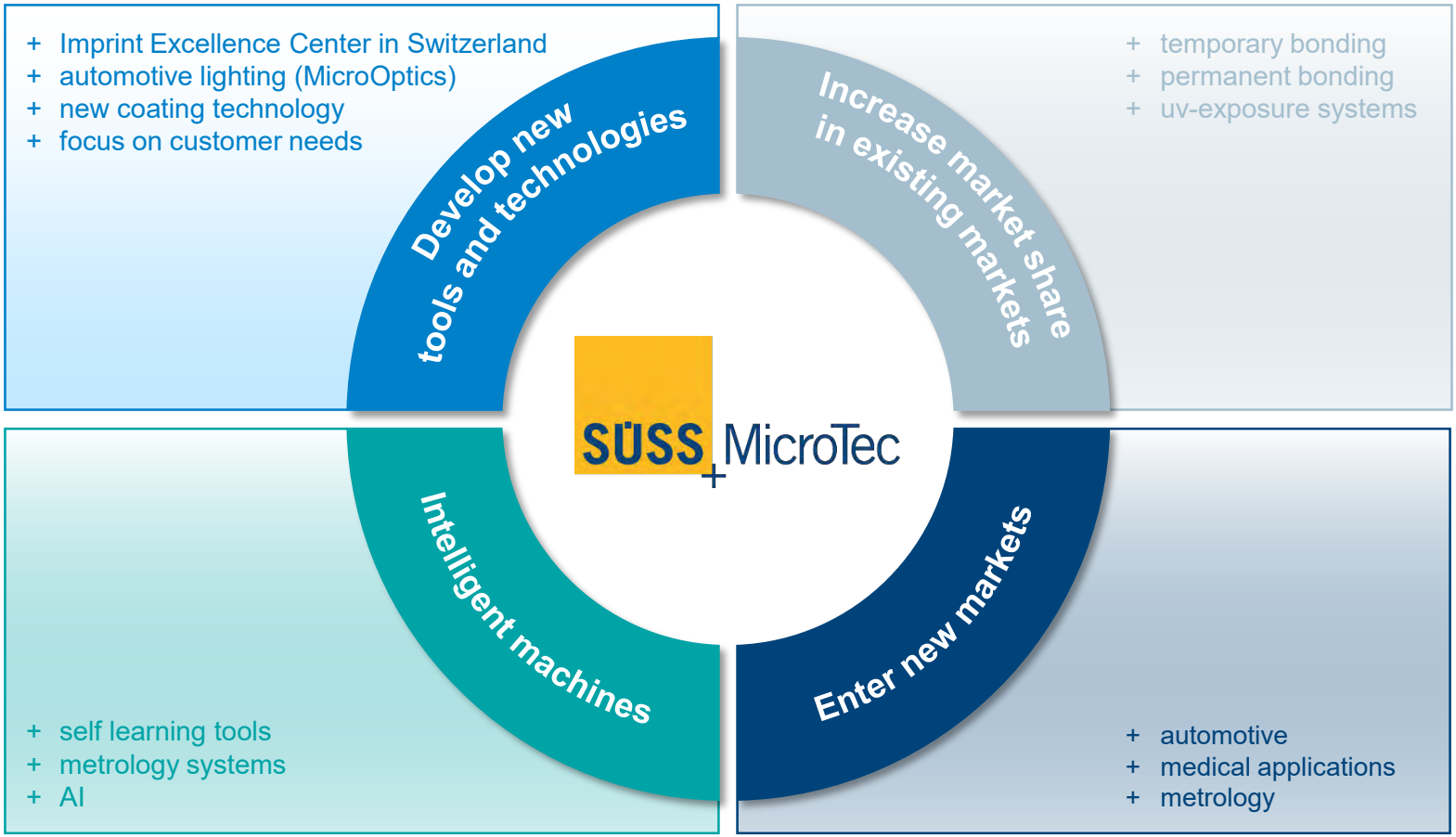
Based on the favorable market trends and our targeted market share gains, we should be able to show sustainable growth of sales over the years to come, always keeping in mind, that the business will remain cyclical

*This chart contains forward-looking targets relating to the business and financial performance of SUSS MicroTec SE. These statements are based on current estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate. Consequently, actual developments as well as performance may differ materially from those which is explicitly or implicitly assumed in this graphic.

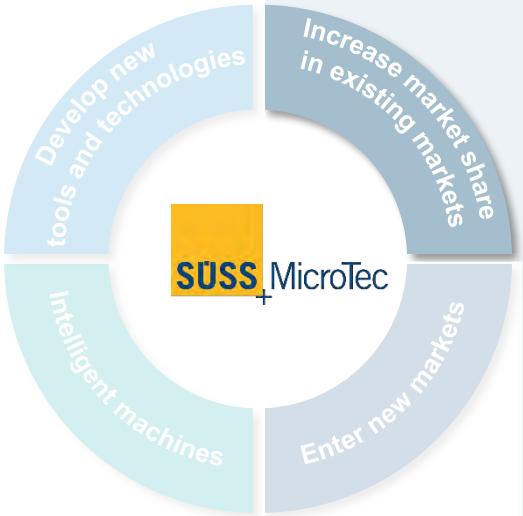
SUSS 2025 – DOUBLE OUR SALES VOLUME

- Customer satisfaction is our highest priority
- Convince as solutions provider
- Enter new business fields
- Establish co-operations with leading semiconductor suppliers
- Develop / acquire new technologies to improve our core products
- Increase production capacity by outsourcing
- Establish a production site for final assembly in Asia

BUILDING BLOCKS OF OUR STRATEGY



BUILDING BLOCKS OF OUR STRATEGY - BONDER

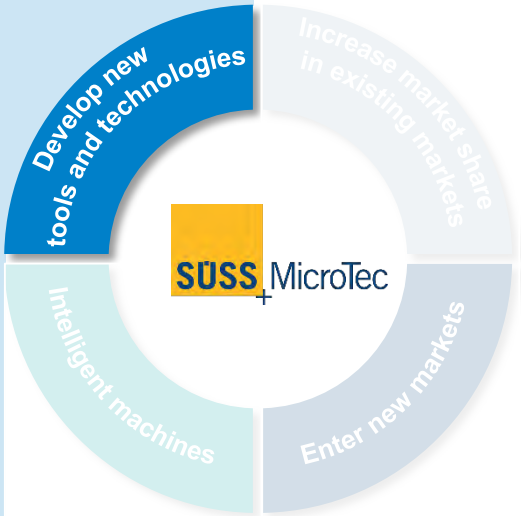


- Maintain and expand market position in temporary bonding
- Penetrate into MEMS applications with permanent bond systems
- Self learning machines and adaptive process improvements
- Completion of 200mm permanent bond platform with scaling to 300mm possible

XBS200
permanent bonding system

BUILDING BLOCKS OF OUR STRATEGY - COATER

- Maintain market share at existing customers
- Mid-term: increase market share in AdP and MEMS via new coating technology with improved cost of ownership
- Self learning and -improving machines
- Cost reduction (e.g. via outsourcing)
- Longer-term: enter new application fields with new coating technology



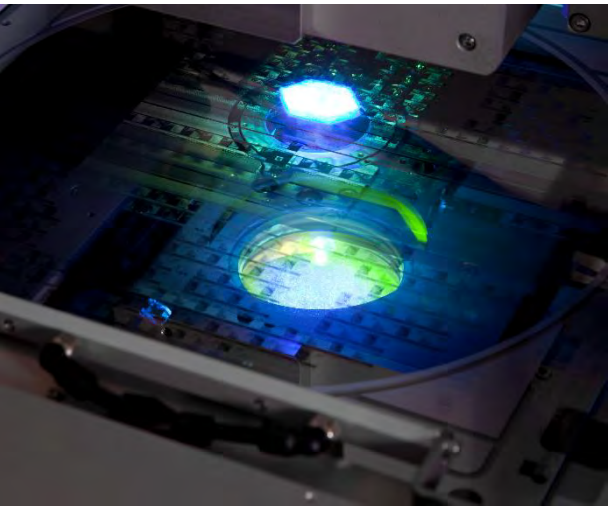
ACS200 Gen3
coater / developer

BUILDING BLOCKS OF OUR STRATEGY - SCANNER

- + **Successful delivery of upgrade kit to lead customer**
- + **Evaluation tool placed at this customer**
- + **Move into volume production with lead customer**
- + **Establish a strong market position in uv-projection exposure**

DSC300 Gen3
UV-projection scanner

UV – PROJECTION SCANNER

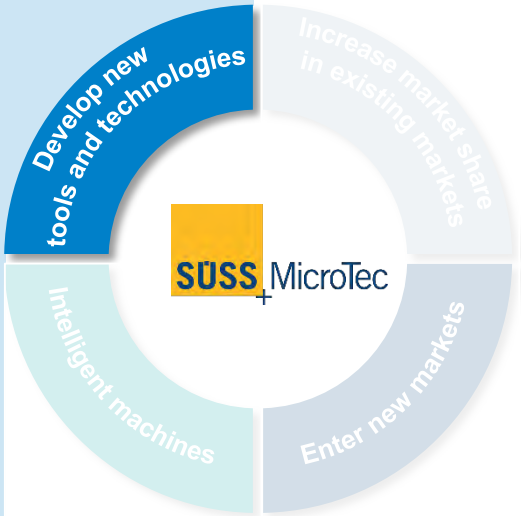


- Target markets: advanced packaging (FOWLP, Cu-pillar…)
- Package sizes are increasing (package size gets larger than step field of conventional 1x stepper)
- Scanner is ideal exposure tool to address large package sizes
- High resolution and overlay
- Throughput of our DSC300 Gen3 increased considerably
- Excellent cost of ownership

Our UV – projection scanner is THE tool to address next generation exposure requirements

BUILDING BLOCKS OF OUR STRATEGY – HIGH VOLUME IMPRINT ON BASIS OF OUR MASK ALIGNER

- Establish an Imprint Excellence Center in Switzerland
- Utilize our mask aligner platform to offer imprint processes and solutions
- High quality and low volume production



BUILDING BLOCKS OF OUR STRATEGY - MICROOPTICS

- Enter automotive market for lighting solutions
- Automotive qualification obtained in 2018
- First orders for light carpet have been placed
- Other automotive lighting solutions are possible

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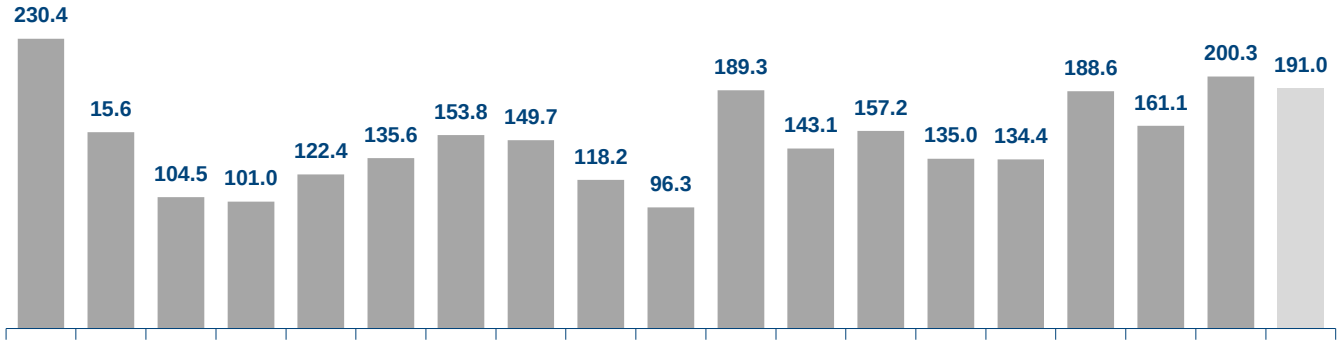
KEY GROUP FIGURES 9M 2018

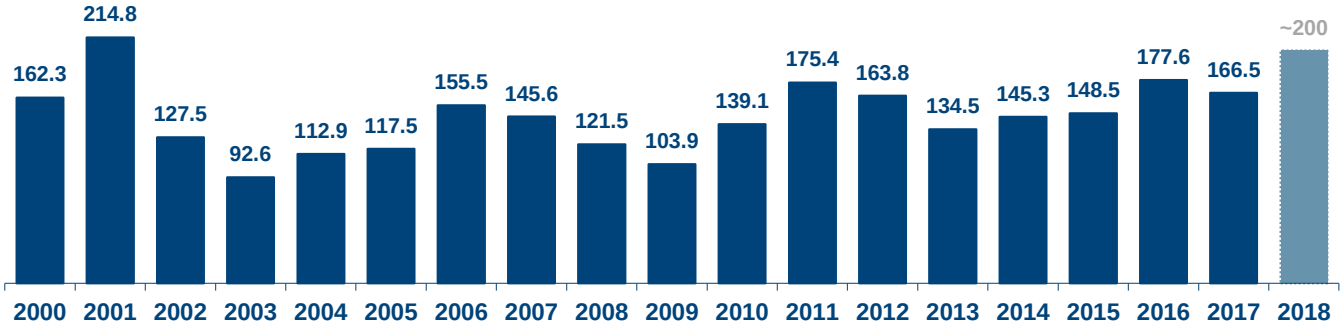
in € million	Q3 2018	Q3 2017	*delta 9M 2018/ 9M 2017*	9M 2018	9M 2017	in %
Order Intake	**47.0**	**36.9**	***+27.4%***	**125.2**	**131.4**	**-4.7%**
Order Backlog 9/30	**--**	**--**	**--**	**119.5**	**117.7**	**1.5%**
Revenue	**41.9**	**47.1**	***-11.0%***	**139.3**	**113.4**	**22.8%**
EBIT	**-0.7**	**7.0**	**--**	**6.9**	**8.6**	**-19.8%**
EBIT in % of Sales	*-1.7%*	*14.9%*	*-16.5%pts*	*5.0%*	*7.6%*	*-2.6%pts*
adjusted EBIT*	**-0.1**	**5.0**	**--**	**7.5**	**6.6**	**-13.6%**
adj. EBIT in % of Sales	*-0.02%*	*10.6%*	*--*	*5.4%*	*5.8%*	*-0.4%pts*
Earnings after tax	**-0.8**	**4.5**	**--**	**3.4**	**3.8**	**-10.5%**
EPS in €	**-0.04**	**0.24**	**--**	**0.18**	**0.20**	**-10.0%**
Free Cash Flow	**-6.8**	**6.3**	**--**	**-22.7**	**0.7**	**--**
Net Cash	**--**	**--**	**--**	**10.4**	**30.9**	**-66.3%**
Employees 9/30	**--**	**--**	**--**	**863**	**762**	**19.6%**

*one-off effect 2017: license income of € 2.0 million
one-off effect 2018: severance payment of appr. € 600 tsd.

LONG TERM BUSINESS DEVELOPMENT I

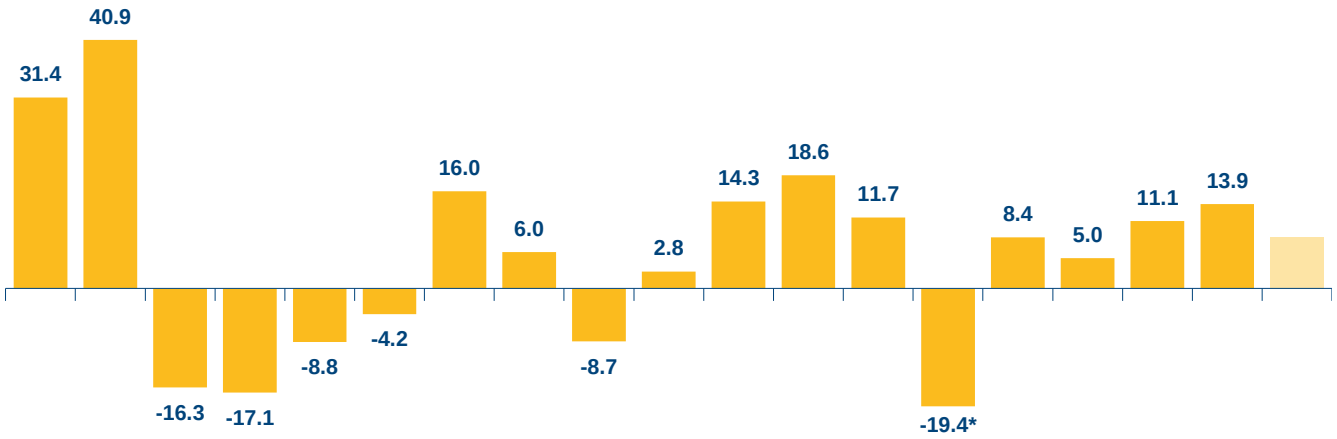


Order Entry
in € million

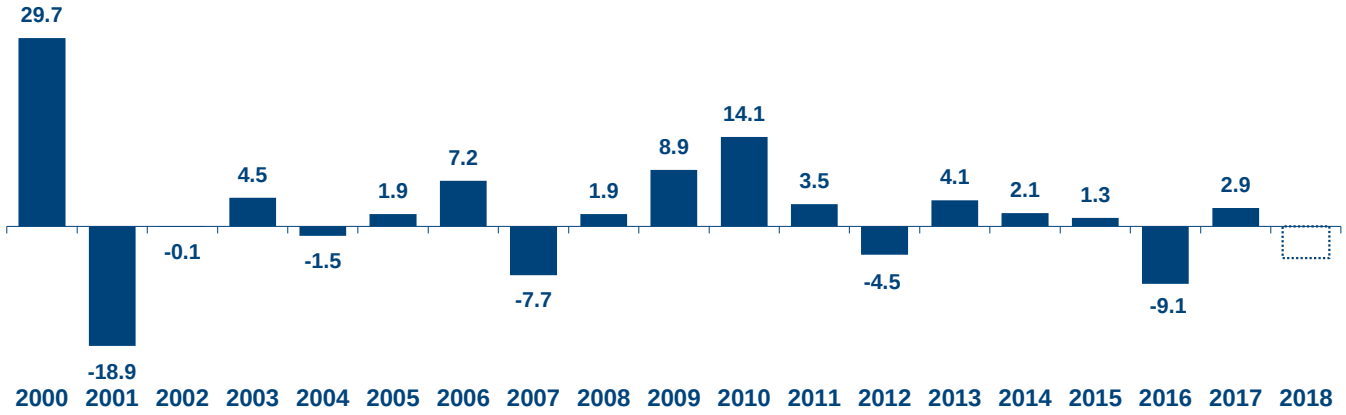


Sales
in € million

LONG TERM BUSINESS DEVELOPMENT II



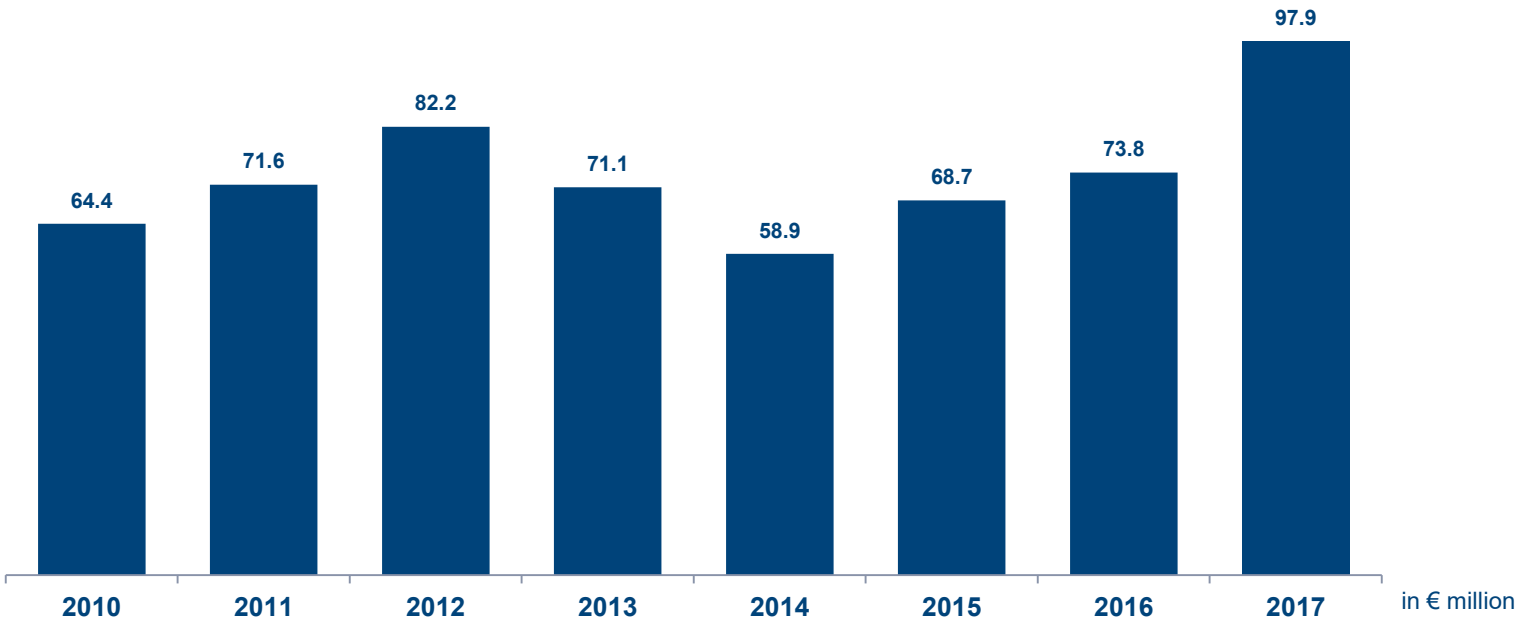
EBIT
in € million



Free Cash Flow
in € million

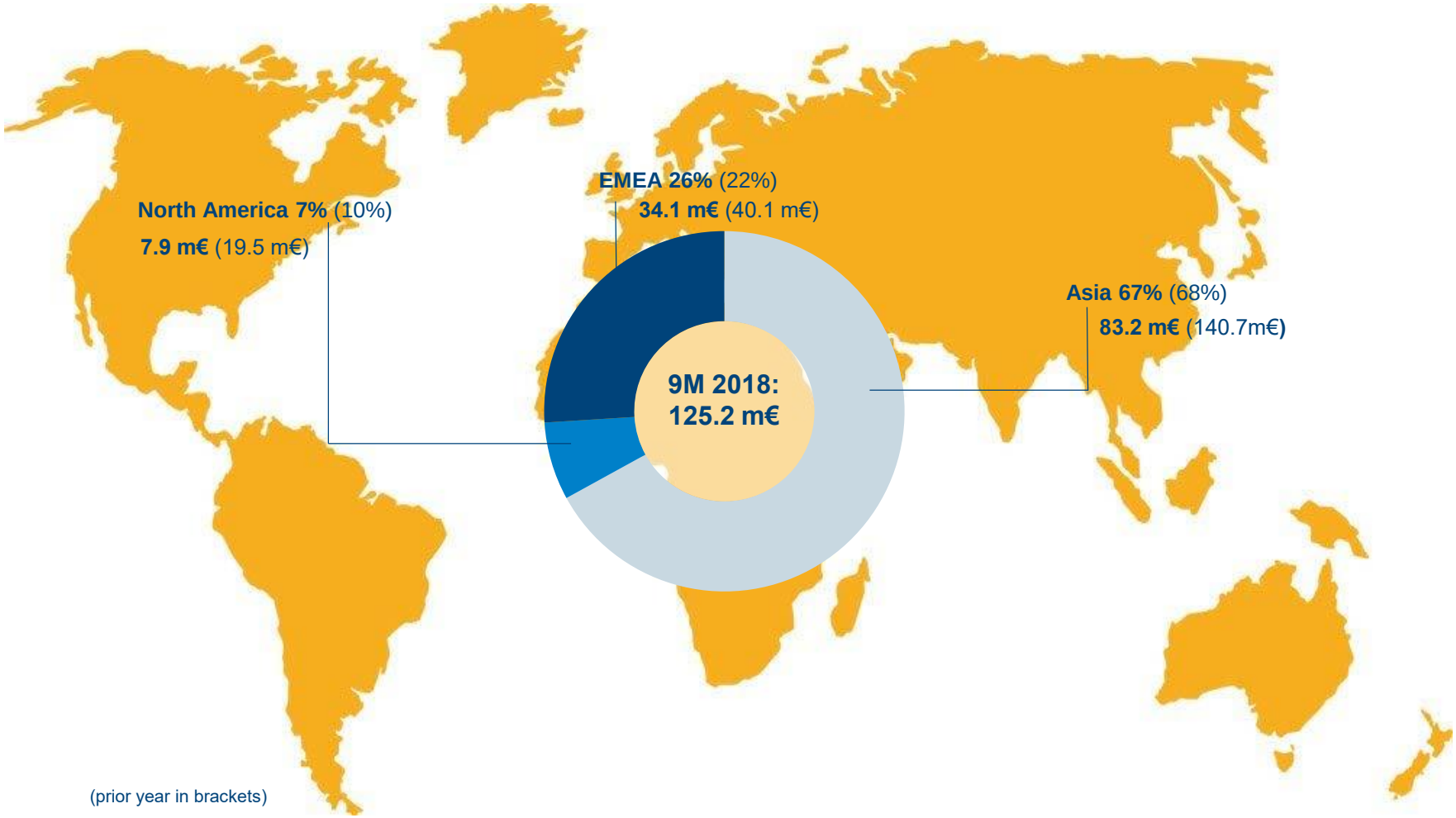
* EBIT 2013: one-off effect from restructuring the product line permanent bonding (€ -13.2 million)

INVENTORY DEVELOPMENT



- Inventory went up because of high order backlog
- Increased number of valuation and demonstration tools in the field
- Preproduction of multiple tools in order to meet challenging lead times

ORDER ENTRY BY REGION 9M 2018 (FY2017)

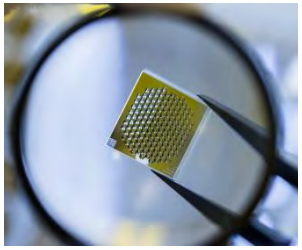


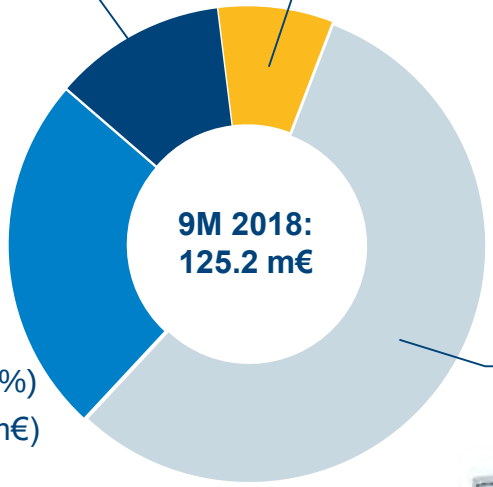
(prior year in brackets)

ORDER ENTRY BY SEGMENT 9M 2018 (FY 2017)

Bonder 12% (20%)
14.5 m€ (36.7 m€)

Others
incl. SMO 8% (7%) **9.7 m€** (11.7 m€)



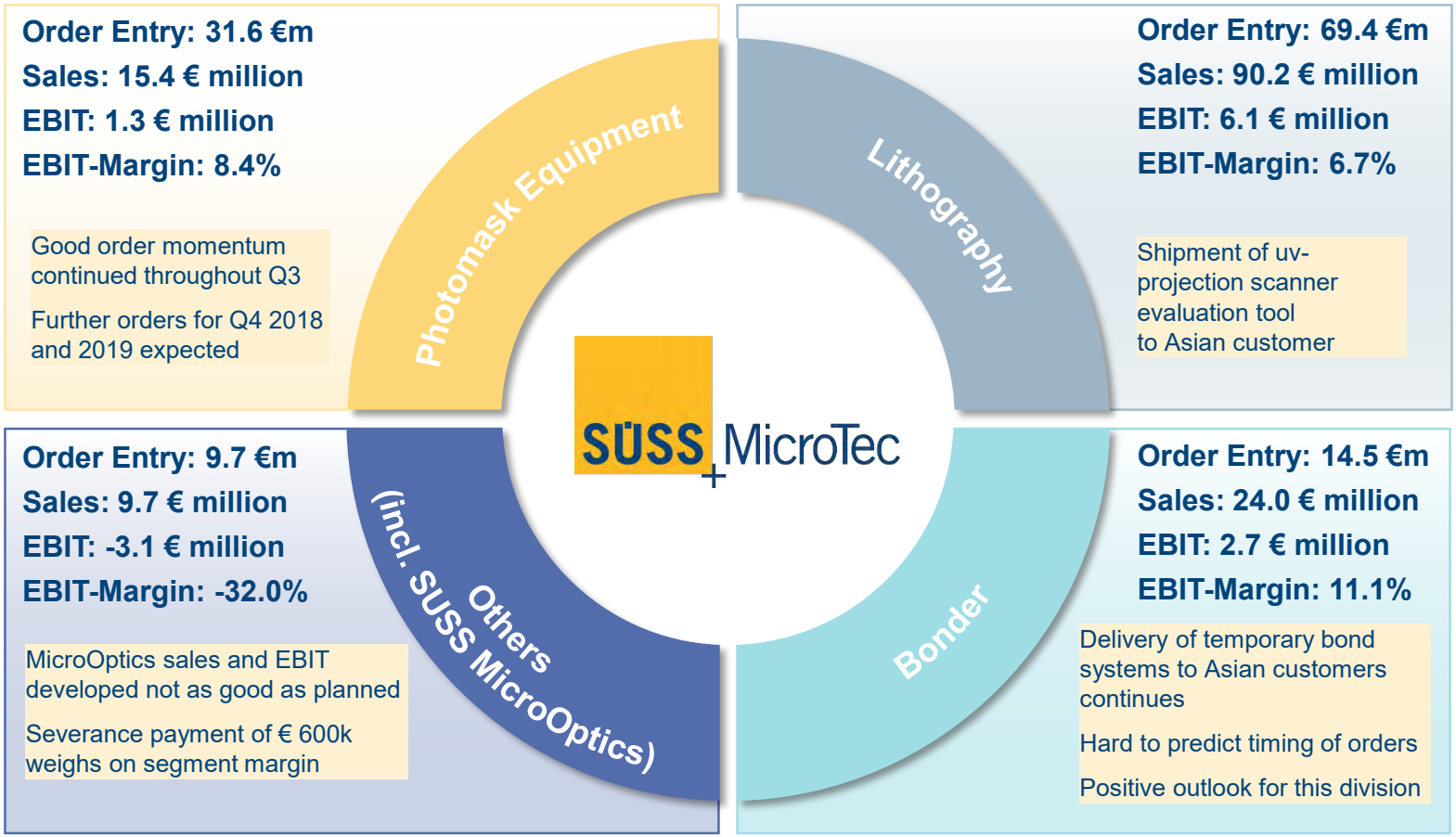


Photomask Equipment 24% (7%)
31.6 m€ (15.7 m€)

Lithography 56% (66%)
69.4 m€ (136.2 m€)

(prior year in brackets)

SEGMENTS DEVELOPMENT IN 9M 2018



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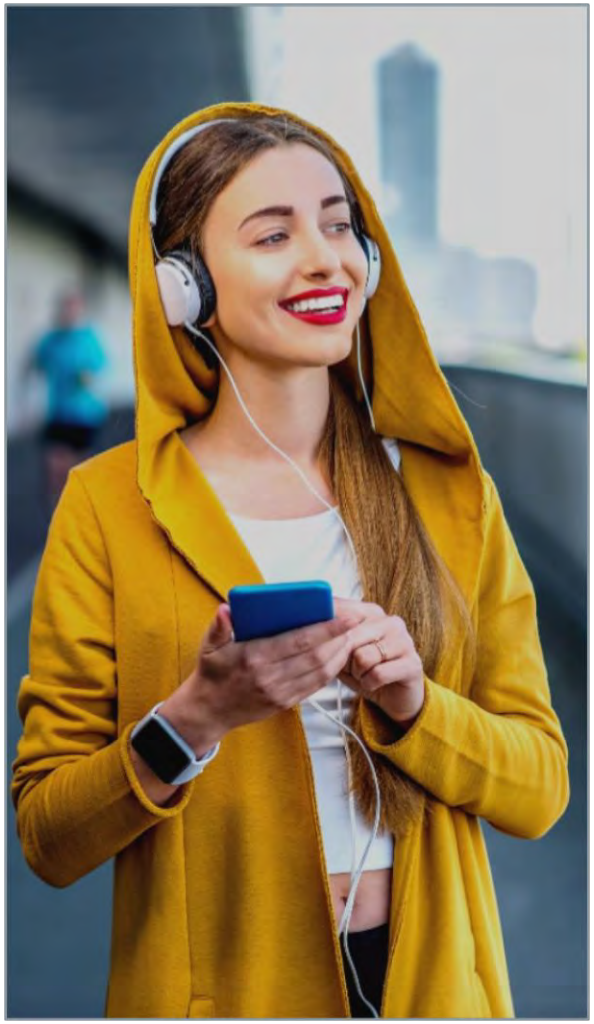
MARKET OUTLOOK

- The semiconductor industry is amidst of a big transition and it is entering a disruptive phase where mobile and other merging mega-drivers, such as big data, 5G, high performance computing (HPC), the internet of things (IoT) as well as smart automotive and smart factory will significantly impact business dynamics an create a tremendous opportunity across the semiconductor supply chain (Yole Sep. 2018)
- Semiconductor market + 13,4% in 2018 to a volume of USD 477 bn and + 2.5% in 2019 (Gartner, January 2019)
- Global Fab equipment spending +9,7% in 2018 to a volume of USD 62.1 bn and -4.0% in 2019 (Semi, December 2018)
- More than Moore (MtM) equipment (lithography tools and bonders) to grow by 10% annually (CAGR 2017 – 2023) to an equipment market volume of appr. USD 750 million (Yole, Oct. 2018)
- 3D TSV and Fan-out markets are expected to grow by a CAGR of 29% and 15% respectively from 2017 – 2023 (Yole, Sep. 2018)

OUTLOOK 2018

- **Fiscal year 2018:** preliminary Sales ~ € 200 million (old method: € 213 million)
  preliminary EBIT-margin ~ 4.2% (old method: € 7.3%)
- **Q4 2018 + Q1 2019:** Order entry of more than € 90 million (Q4 2018: € 64.8 million)

INVESTMENT HIGHLIGHTS



Situation:

+ Highly innovative markets
+ Megatrends support business case
+ International customers
+ Increased R&D
+ Long term growth targets

Outlook:

+ Semiconductor market growth will continue
+ IOT, digitization, AI, mobility,… are just taking off
+ Entering new business fields with established and new products
+ Imprint excellence center starts operating in Switzerland
+ More volume orders for temporary bonding systems to come
+ Position permanent bonding systems in market
+ 2019 will be the decisive year for uv-projection scanners

SUSS MICROTEC INVESTOR PRESENTATION

Back up

INVESTOR RELATIONS INFORMATION

Contact

Franka Schielke

Tel.: +49 89 32007- 161
Fax.: +49 89 32007- 451
Email: franka.schielke@suss.com

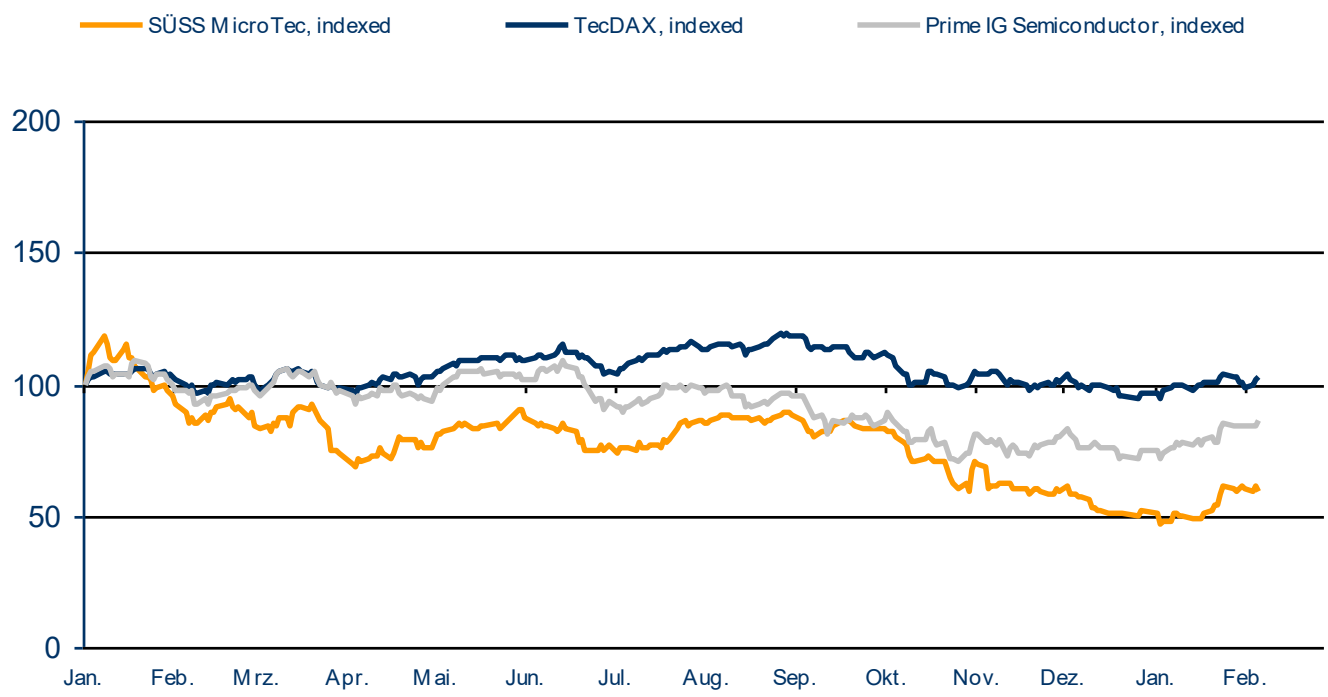
SÜSS MicroTec SE
Schleissheimer Strasse 90
85748 Garching
Germany
www.suss.com

Financial Calendar 2019

Annual Report 2018	27 Mar
Quarterly Announcement 2019 (Q1)	8 May
Annual General Meeting 2019, Munich	6 Jun
Interim Report 2019	7 Aug
Quarterly Announcement 2019 (Q3)	7 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SUSS MicroTec Share at January 2, 2018: 16.78 €)



Major Shareholders > 3%:

Internat. Kap. Anl. (INKA)
Universal-Investment
Luxempart
Kempen Oranje
Sycomore Asset Man.
Janus Henderson Group
Dimensional Funds
Lupus Alpha
Hansa Invest
Gerlin NV

Average daily trading volume January 2018 – January 2019: ~ 65.200

SEGMENTS, ORDER ENTRY AND SALES FULL YEAR 2017

Segments

Photomask Equipment

Order Entry: 15.7 € million
Sales: 19.7 € million
EBIT: 5.1 € million
EBIT-Margin: 25.9%
*Adj. EBIT-Margin: 15.7%**
**€ -2m licence agreement*

Lithography

Order Entry: 136.2 € million
Sales: 112.8 € million
EBIT: 6.3 € million
EBIT-Margin: 5.6%
*Adj. EBIT-Margin: 14.5%**
**€ +10m losses Photonic Systems*

Bonder

Order Entry: 36.7 € million
Sales: 22.1 € million
EBIT: 3.3 € million
EBIT-Margin: 14.9%
*Adj. EBIT-Margin: 10.4%**
**€ -1m extraordinary margin perm. bonder*

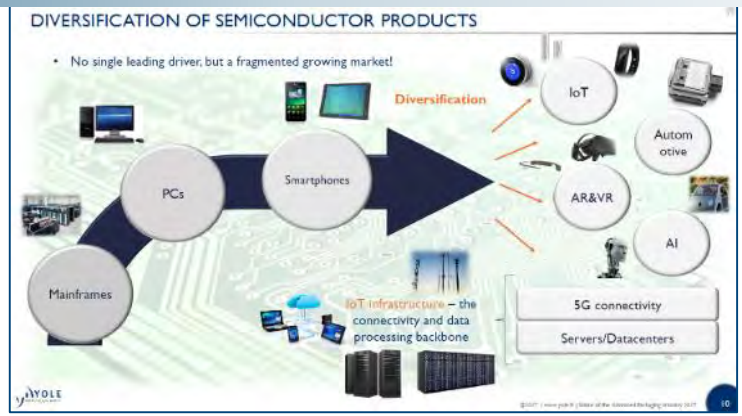
SUSS MicroTec Group FY 2017**

Order Entry: 200.3 € million
Sales: 166.5 € million
EBIT: 13.9 € million
EBIT margin: 8.3%
Adj. EBIT-Margin: 12.6%

** Including Others (2017: order entry € 11.7 million, sales € 11.9 million, EBIT € -0.8 million)

OUR GROWTH DRIVERS

Advanced Packaging



RF MEMS

3D Packaging

FOWLP

SEMICONDUCTOR EQUIPMENT INDUSTRY

Front end	Mid end	Back end
Major players are: + ASML + Applied Materials + Tokyo Electron + Canon + ...	**Major players are:** + SUSS MicroTec + EVG + Veeco + Tok + SMEE + King Semi, …	**Major players are:** + BE Semiconductor + Cascade Microtec + Disco + …
Processing steps are: + Lithography (creation of IC; nm) + Dry etch + Deposition + Metrology/inspection + …	**Processing steps are:** + Lithography (flip chip, WLP; µ) + Wafer bonding + Creation of micro- structures, MEMS and RF-MEMS + …	**Processing steps are:** + Wafer dicing + Die bonding + Assembly / packaging + Metrology / final test + …

SUSS MICROOPTICS – GROWTH DRIVER AUTOMOTIVE LIGHTING

Automotive Lighting

+ Light Carpet (External and internal)
+ Front Lights (LED Matrix and Laser Light)

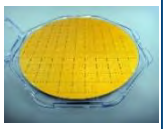
Low volume high quality

+ LVHQ is the traditional Micro-Optics business, which addresses profitable niche markets with low growth but high margins

SMO products and end applications:

Microlens Array
13x13mm²

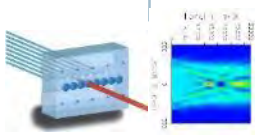
Asclepion TattooStar

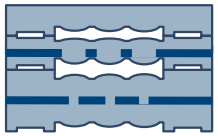


ROE + DOE
40x50mm²

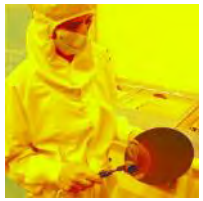
ASML 193nm wafer stepper

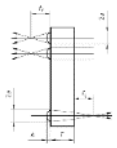
SUSS IMPRINTING EXCELLENCE CENTER
CUSTOMER SERVICES @ SUSS MICROOPTICS PRODUCTION

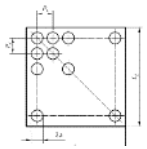


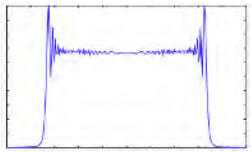


Wafer-Level Optics (WLO)
→ Aperture layers in bulk material
→ Excellent overlay control

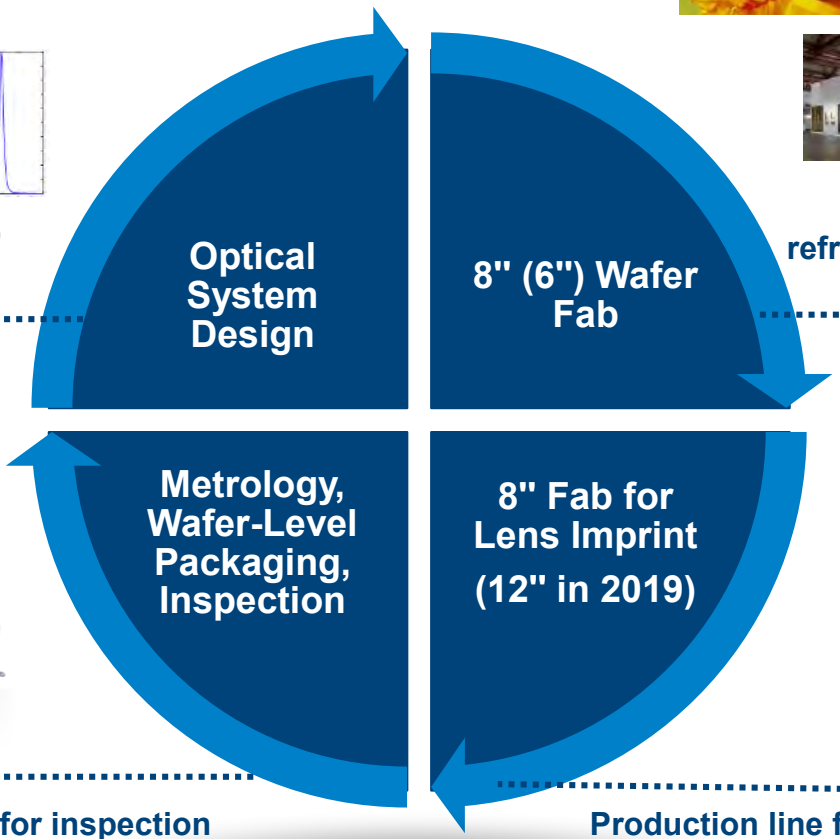




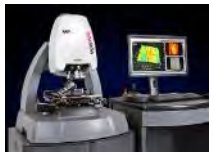


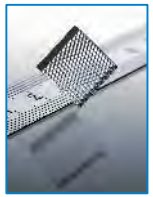


Optical Design, System Design,
Micro-Optics Simulation



Production line high-quality
refractive & diffractive micro-optics
(Fused Silica, Silicon)





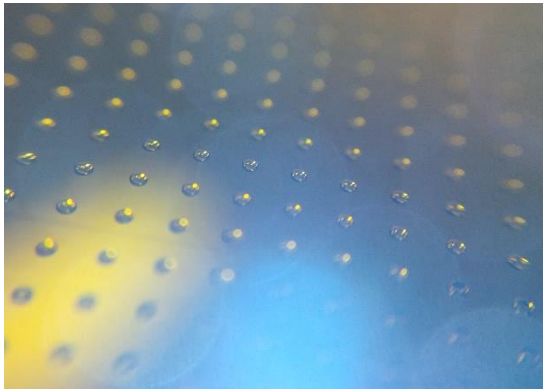
Fully equipped metrology lab for inspection
and sorting of micro-optical components.
(ISO 9001, IATF 16949, Six Sigma)

Production line for micro lens imprint (Polymer),
wafer-level packaging (WLP), dicing
Start-Up service for SUSS customers

MASK ALIGNER – GROWTH DRIVER IMPRINT SOLUTIONS

The flexible imprint portfolio for

- **Nano – Imprint**
- **Micro – Imprint**
- **Optical Assembly**



is covering a wide range of growing applications & markets

LED

(nano)PSS for High Brightness LEDs.

MEMS/NEMS

Nano- and micro-patterning need to be extensively adopted in device manufacturing.

Optoelectronic sensors

Optical nano-gratings are key components for the communication market worldwide.

Microoptics

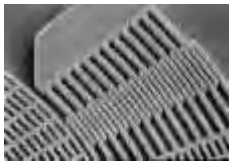
Imprint is essential to fabricate micro-optical devices for wafer-level cameras and image sensors.

Augmented Reality

Imprinted nano-metric DOE de-fractive optical elements are required for the glasses with augmented reality

LITHOGRAPHY PROCESS STEPS: MEMS PRODUCTION

From wafer to airbag sensor



Cleaning, Dehydration Bake → **Coating** → **Exposure** → **Develop-ment** → **Wafer Bonding** → Metal Lift-Off → Inspection / Testing → **Wafer Level Packaging** → Dicing…

Coater / Developer

Mask Aligner

Coater / Developer

Wafer Bonder

Coater / Mask Aligner